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Dual General Purpose Transistors

NPN/PNP Dual (Complementary)

This transistor is designed for general purpose amplifier applications. It is housed in the SOT-563 which is designed for low power surface mount applications.

Features

- Lead-Free Solder Plating
- Low $V_{CE(SAT)}$, < 0.5 V
- These are Pb-Free Devices

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V_{CEO}	-60	V
Collector - Base Voltage	V_{CBO}	– 50	V
Emitter – Base Voltage	V _{EBO}	-6.0	V
Collector Current – Continuous	I _C	-100	mAdc

THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D	357 (Note 1) 2.9 (Note 1)	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	350 (Note 1)	°C/W
Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D	500 (Note 1) 4.0 (Note 1)	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	250 (Note 1)	°C/W
Junction and Storage	T _J , T _{stq}	-55 to +150	°C

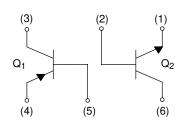
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 @ Minimum Pad.



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SOT-563 CASE 463A STYLE 1

MARKING DIAGRAM



3Z = Specific Device Code

M = Month Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS $(T_A = 25^{\circ}C)$

Characteristic	Symbol	Min	Тур	Max	Unit
Q1: PNP	•				•
Collector–Base Breakdown Voltage $(I_C = -50 \mu Adc, I_E = 0)$	V _{(BR)CBO}	-60	-	-	Vdc
Collector–Emitter Breakdown Voltage $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-50	-	-	Vdc
Emitter–Base Breakdown Voltage $(I_E = -50 \mu Adc, I_E = 0)$	V _{(BR)EBO}	-6.0	-	-	Vdc
Collector–Base Cutoff Current $(V_{CB} = -30 \text{ Vdc}, I_E = 0)$	I _{CBO}	-	-	-0.5	nA
Emitter-Base Cutoff Current (V _{EB} = -5.0 Vdc, I _B = 0)	I _{EBO}	-	-	-0.5	μΑ
Collector–Emitter Saturation Voltage (Note 2) $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	V _{CE(sat)}	-	-	-0.5	Vdc
DC Current Gain (Note 2) (V _{CE} = -6.0 Vdc, I _C = -1.0 mAdc)	h _{FE}	120	-	560	-
Transition Frequency $(V_{CE} = -12 \text{ Vdc}, I_C = -2.0 \text{ mAdc}, f = 30 \text{ MHz})$	f _T	-	140	-	MHz
Output Capacitance $(V_{CB} = -12 \text{ Vdc}, I_E = 0 \text{ Adc}, f = 1 \text{ MHz})$	C _{OB}	-	3.5	-	pF
Q2: NPN	'				
Collector-Base Breakdown Voltage ($I_C = 50 \mu Adc, I_E = 0$)	V _{(BR)CBO}	60	_,		Vdc
Collector-Emitter Breakdown Voltage $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	50			Vdc
Emitter-Base Breakdown Voltage ($I_E = 50 \mu Adc, I_E = 0$)	V _{(BR)EBO}	7.0	-	-	Vdc
Collector-Base Cutoff Current (V _{CB} = 60 Vdc, I _E = 0)	I _{CBO}	-	-	0.5	μΑ
Emitter-Base Cutoff Current $(V_{EB} = 7.0 \text{ Vdc}, I_B = 0)$	I _{EBO}	-	-	0.5	μΑ
Collector-Emitter Saturation Voltage (Note 3) $(I_C = 50 \text{ mAdc}, I_B = 5.0 \text{ mAdc})$	V _{CE(sat)}	_	_	0.4	Vdc
DC Current Gain (Note 3) (V _{CE} = 6.0 Vdc, I _C = 1.0 mAdc)	h _{FE}	120	-	560	_
Transition Frequency ($V_{CE} = 12 \text{ Vdc}, I_{C} = 2.0 \text{ mAdc}, f = 30 \text{ MHz}$)	f _T	-	180	-	MHz
Output Capacitance (V _{CB} = 12 Vdc, I _C = 0 Adc, f = 1 MHz)	C _{OB}	-	2.0	-	pF

^{2.} Pulse Test: Pulse Width \leq 300 μ s, D.C. \leq 2%.

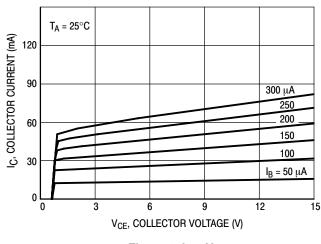
ORDERING INFORMATION

Device	Package	Shipping [†]
EMZ1DXV6T1	SOT-563*	4000 Units / Tape & Reel
EMZ1DXV6T1G	SOT-563*	4000 Units / Tape & Reel
EMZ1DXV6T5	SOT-563*	8000 Units / Tape & Reel
EMZ1DXV6T5G	SOT-563*	8000 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb–Free.

^{3.} Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.

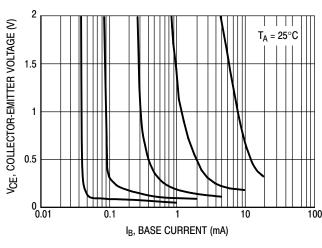
TYPICAL ELECTRICAL CHARACTERISTICS - Q1, PNP



1000 T_A = 75°C T_A = 25°C T_A = 25°C T_A = 25°C T_A = 25°C T_A = 0.10 V T_A = 0.1

Figure 1. I_C – V_{CE}

Figure 2. DC Current Gain



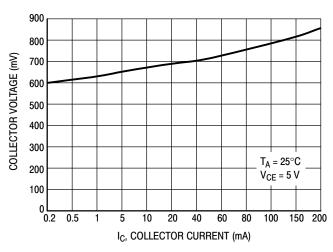
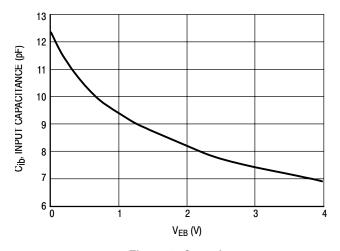


Figure 3. Collector Saturation Region

Figure 4. On Voltage



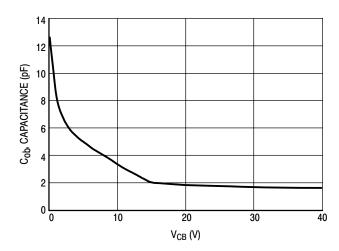
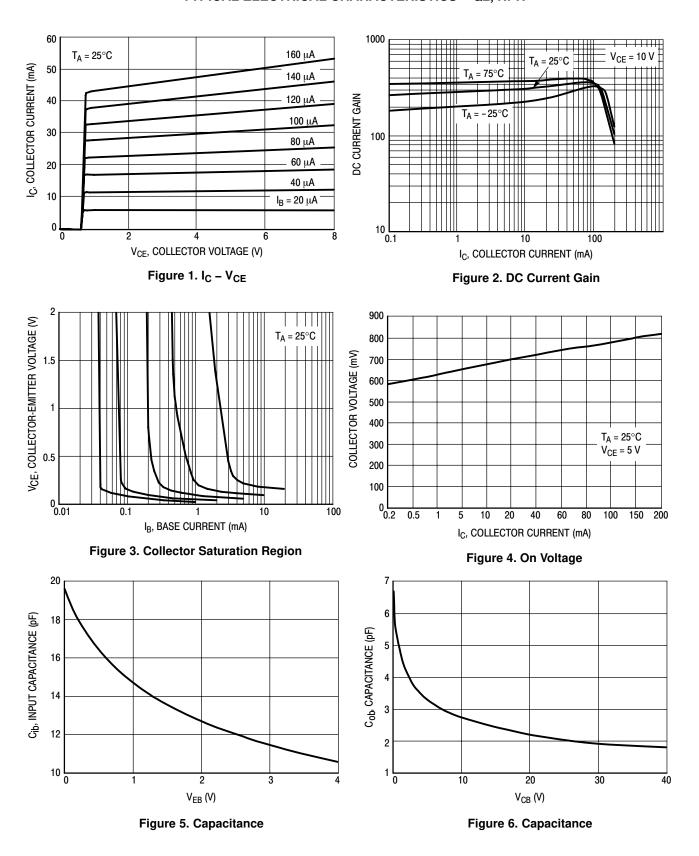


Figure 5. Capacitance

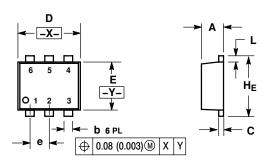
Figure 6. Capacitance

TYPICAL ELECTRICAL CHARACTERISTICS - Q2, NPN



PACKAGE DIMENSIONS

SOT-563, 6 LEAD CASE 463A-01 ISSUE F



NOTES

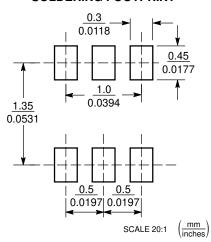
- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.021	0.023
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.12	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.062	0.066
E	1.10	1.20	1.30	0.043	0.047	0.051
е		0.5 BSC 0.02 BSC				
L	0.10	0.20	0.30	0.004	0.008	0.012
He	1.50	1 60	1 70	0.059	0.062	0.066

STYLE 1: PIN 1. EMITTER 1

- 2. BASE 1 3. COLLECTOR 2
- 4. EMITTER 2
- BASE 2 COLLECTOR 1

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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